

LNPTM THERMOCOMPTM COMPOUND CX05470

CF-1004 ZS

DESCRIPTION

LNP THERMOCOMP CX05470 compound is based on Polystyrene (PS) resin containing 20% glass fiber.

GENERAL INFORMATION	
Features	No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polystyrene (PS)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Automotive	Automotive Interiors
Building and Construction	Building Component
Consumer	Sport/Leisure
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Material Handling

TYPICAL PROPERTY VALUES

UNITS TEST METHODS PROPERTIES TYPICAL VALUES MECHANICAL⁽¹⁾ Flexural Strength, 2 mm/min 85 MPa ISO 178 6320 MPa ISO 178 Flexural Modulus, 2 mm/min Tensile Stress, break, 5 mm/min 52 MPa ISO 527 ISO 527 Tensile Strain, break, 5 mm/min 1.1 % Tensile Modulus, 1 mm/min 6800 MPa ISO 527 Tensile Modulus, 5 mm/min 7100 MPa ASTM D638 MPa Tensile Stress, brk, Type I, 5 mm/min 56 ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 1.2 ASTM D638 % Flexural Strength, 1.3 mm/min, 50 mm span 90 MPa ASTM D790 Flexural Modulus, 1.3 mm/min, 50 mm span 6480 MPa ASTM D790 IMPACT (1) Izod Impact, notched 80*10*4 +23°C 3 kJ/m² ISO 180/1A Izod Impact, unnotched 80*10*4 +23°C 9 kJ/m² ISO 180/1U 2 ISO 6603 Multiaxial Impact Izod Impact, unnotched, 23°C 156 J/m ASTM D4812 Izod Impact, notched, 23°C 36 J/m ASTM D256 8 ASTM D3763 Instrumented Dart Impact Total Energy, 23°C I. THERMAL (1) 97 °C ISO 75/Bf HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm °C ISO 75/Af HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm 92 CHEMISTRY THAT MATTERS © 2024 Copyright by SABIC. All rights reserved

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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT, 0.45 MPa, 3.2 mm, unannealed	97	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	93	°C	ASTM D648
CTE, -30°C to 30°C, flow	5.60E-05	1/°C	ASTM D696
CTE, -30°C to 30°C, xflow	6.90E-05	1/°C	ASTM D696
PHYSICAL ⁽¹⁾			
Moisture Absorption (23°C / 50% RH)	0.07	%	ISO 62
Density	1.18	g/cm³	ASTM D792
Specific Gravity	1.18	-	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.06	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1 - 0.4	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.2 – 0.5	%	ASTM D955
INJECTION MOLDING (3)			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	250	°C	
Front - Zone 3 Temperature	265 – 275	°C	
Middle - Zone 2 Temperature	245 – 255	°C	
Rear - Zone 1 Temperature	220 – 230	°C	
Mold Temperature	40 – 65	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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